To the Director, U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name and address of receiving party(ies):
   Name: QUALCOMM MEMS Technologies, Inc.
   Street Address: 5775 Morehouse Drive
   City: San Diego State: CA
   ZIP: 92121
   Additional name(s) of receiving party(ies) attached?
   ( ) Yes (X) No

2. Nature of conveyance:
   (X) Assignment
   ( ) Security Agreement
   ( ) Merger
   ( ) Change of Name
   ( ) Other:
   Execution Date: (List as in section 1 if multiple signatures)
   1. June 9, 2010
   2. June 8, 2010
   3. June 8, 2010
   4. June 9, 2010
   5. June 14, 2010

3. Party to whom correspondence concerning document should be mailed:
   Customer No. 59,747
   Address: Knobbe, Martens, Olson & Bear, LLP
   2040 Main Street, 14th Floor
   Irvine, CA 92614
   Return Fax: (949) 760-9502
   Attorney’s Docket No.: QCO.280A/091552

4. US or PCT Application number(s) or US Patent number(s):
   (X) Patent Application No.: 12/789,415
   Filing Date: May 27, 2010
   Additional numbers attached?
   ( ) Yes (X) No

5. Total number of applications and patents involved: 1

6. Total fee (37 CFR 1.21(h)): $40
   (X) Authorized to be charged to deposit account

7. Deposit account number: 11-1410
   Please charge this account for any additional fees which may be required, or credit any overpayment to this account.

8. Statement and signature.
   To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.

   Gregory A. Hermanson
   Name of Person Signing
   53,018
   Registration No.

   Signature
   June 22, 2010
   Date

Total number of pages including cover sheet, attachments and document: 4
ASSIGNMENT

WHEREAS, I, Ion Bita, a Romanian citizen, having a mailing address at 2581 Junction Avenue, San Jose, California 95134, and residing at San Jose, California; Sapna Patel, a US citizen, having a mailing address at 2581 Junction Avenue, San Jose, California 95134, and residing at Fremont, California; Clayton Ka Tsun Chan, a US citizen, having a mailing address at 2581 Junction Avenue, San Jose, California 95134, and residing at Fremont, California; Surya Prakash Ganti, an Indian citizen, having a mailing address at 2581 Junction Avenue, San Jose, California 95134, and residing at Los Gatos, California; and Brian W. Arbuckle, a US citizen, having a mailing address at 2581 Junction Avenue, San Jose, California 95134, and residing at San Jose, California; have invented certain new and useful improvements in ILLUMINATION DEVICES AND METHODS OF FABRICATION THEREOF for which I caused to be filed an application for Letters Patent in the United States; and I hereby authorize and request the attorneys of Knobbe, Martens, Olson & Bear, LLP, Customer No. 59,747, to insert here in parentheses (Application Number 12/789,415, filed May 27, 2010) the filing date and application number of said application when known;

AND WHEREAS, QUALCOMM MEMS Technologies, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, with its principal place of business at 5775 Morehouse Drive, San Diego, California 92121, U.S.A, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer, and set over, unto the said ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest throughout the world in, to, and under the said improvements, and the said application and all provisional application(s) to which said Application claims, or is entitled to claim, priority, and all divisions, renewals, and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals, and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

AND I DO HEREBY sell, assign, transfer, and convey to the said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to the said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.
AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives, and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 9th day of June 2010.

Ion Bita

Sapna Patel

Clayton Ka Tsun Chan

Surya Prakash Ganti

Brian W. Arbuckle
IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS Technologies, Inc. this day of ______________, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title: